

English

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Product Change Notification - JAON-07YGZF687 [\(Printer Friendly\)](#)

**Date:** 13 Jan 2016

**Notification subject:** CCB 1833 Initial Notice: Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 200K wafer technology available in 8L PDIP package at MMT assembly site

**Notification text:** **PCN Status:**  
Initial notification

**Microchip Parts Affected:**  
Please open the attachments found in the attachments field below labeled as PCN\_#\_Affected\_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

**Description of Change:**  
Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 200K wafer technology available in 8L PDIP package at MMT assembly site.

**Pre Change:**  
Gold (Au) or Palladium coated copper wire (PdCu) bond wire

**Post Change:**  
Palladium coated copper with gold flash (CuPdAu) bond wire

**Pre and Post Change Summary:**

	Pre Change	Post Change
<b>Assembly Site</b>	MMT assembly site	MMT assembly site
<b>Wire material</b>	Au wire or PdCu wire	CuPdAu wire
<b>Die attach material</b>	CRM-1064L	CRM-1064L
<b>Molding compound material</b>	GE800	GE800
<b>Lead frame material</b>	CDA194	CDA194

**Impacts to Data Sheet:**  
None

**Reason for Change:**  
To improve manufacturability by qualifying Palladium coated copper with gold flash (CuPdAu) bond wire.

**Change Implementation Status:**  
In Progress

**Estimated First Ship Date:**  
April 20, 2016 (date code: 1616)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

**Summary Table:**

	January 2016				February 2016				March 2016					April 2016			
WW	01	02	03	04	05	06	07	08	09	10	11	12	13	14	15	16	17
Initial PCN Issue Date		X															
Qual Report Availability							X										
Final PCN Issue Date										X							
Implementation Date																X	

**Markings to Distinguish Revised from Unrevised Devices:**  
Traceability code

**Revision History:**

**January 13, 2016:** Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

**Attachment(s):**

[PCN\\_JAON-07YGZF687\\_Qual\\_Plan.pdf](#)  
[PCN\\_JAON-07YGZF687\\_Affected\\_CPN.pdf](#)  
[PCN\\_JAON-07YGZF687\\_Affected\\_CPN.xls](#)

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